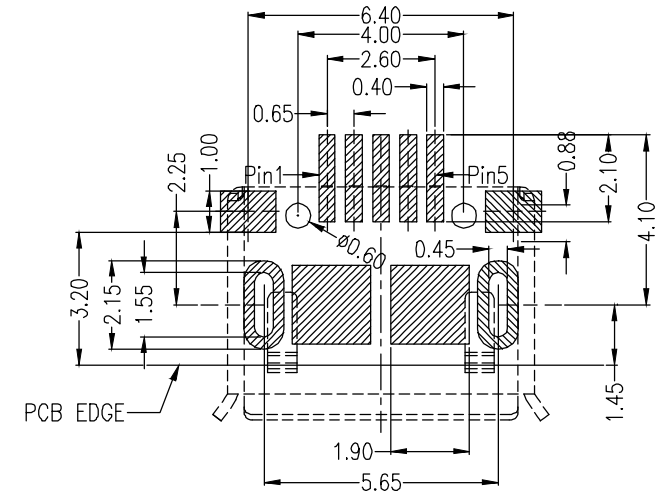
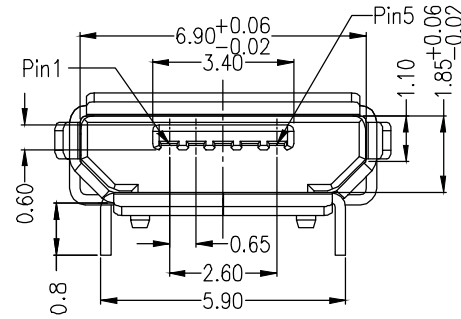
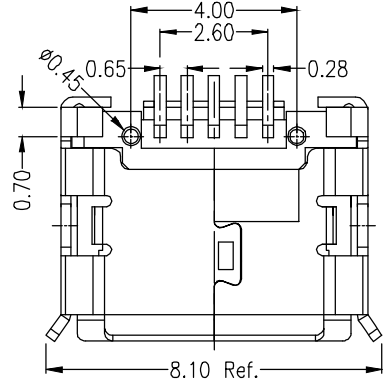
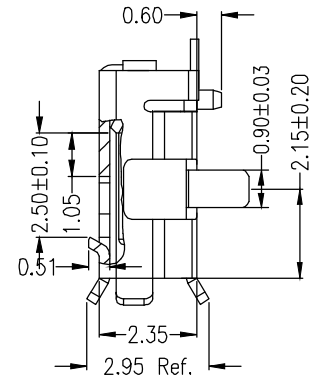
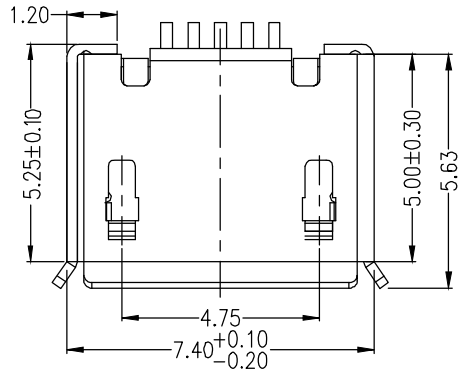
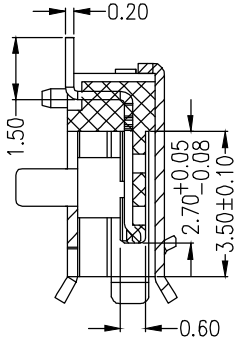
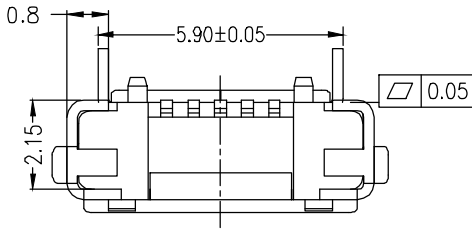


REV.	ECN. NO.	MODIFY. CONTENT	DATE
A		NEW	2012/04/13



RECOMMENDED PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30°C~80°C

GENERAL TOLERANCE		DWG NO.	JYSA0413-02	APPD:	WIND	Scale	1:1
X. ±0.45	x. °±5°	Title	MICRO USB 5P SMT+DIP (5.65插脚间距) 有柱卷边	CHKD:		UNIT	mm
.XX±0.35	.x°±2°			DR:			
.XX±0.25	.xx°±1°	Part NO.	JYS-USB565-050	Date	2012/04/13		
.XXX±0.15	.xxx°±0.5°						
SHEET	1/1			JYSCONN Electronics Co., LTD.			